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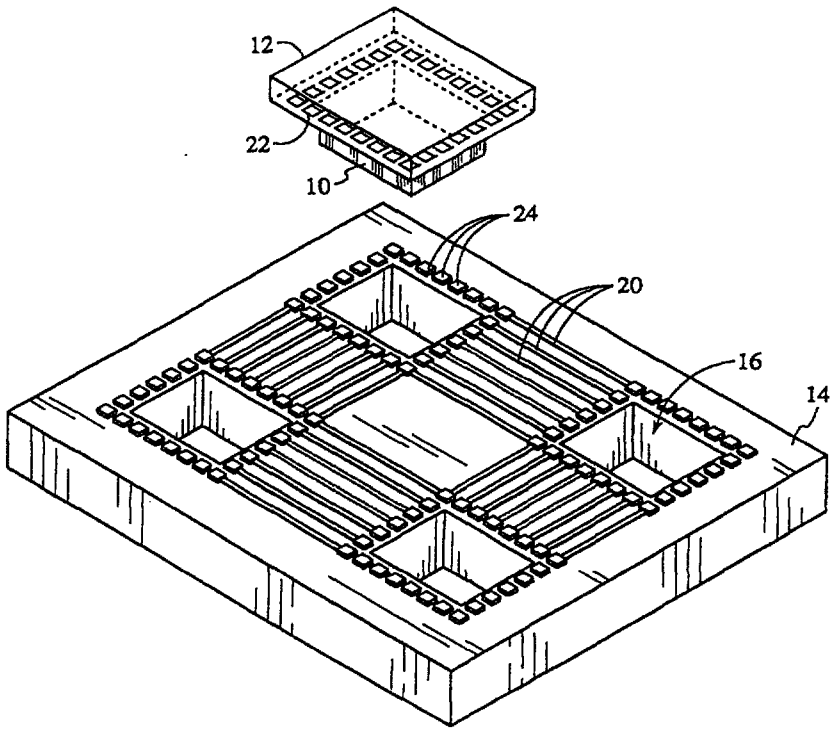
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(57) Abstract

A system and method for efficiently interconnecting a plurality of ICs (10), thereby improving the electrical performance of the overall system while reducing contact degradation due to stress that results from differences in the coefficients of thermal expansion of the various components during thermal cycling.